

Amendments to the Specification

On page 2, line 1, in the "Cross Reference To Related Applications" added by the Preliminary Amendment dated November 21, 2003, please make the following changes.

Cross Reference To Related Applications

This application is a division of serial no. 10/094,161, filed 03/06/2002, Patent No. 6,908,784.

This application is related to serial no. 10/719,876, filed 11/21/03, to serial no. 11/052,279, filed 02/07/05, to serial no. 11/050,857, filed 02/07/05, and to serial no. 11/146,397 filed 06/06/2005.

In the "Brief Description of the Drawings" on page 11, lines 11-12, please make the following change:

Figure ~~6~~ 7 is a block diagram illustrating steps in the first embodiment fabrication method;

In the paragraph on page 60, lines 13-26 please make the following change.

Next, as shown in Figures 19B and 20B, planarized contact bumps 24PGA are formed on the die contacts 18PGA in electrical communication with the conductive vias 68PGA. The contact bumps 24PGA can be formed substantially as previously described for the contact bumps 24A ~~24PGA~~ in Figure 8A. As also shown in Figure 19B, polymer filled trenches 28PGA are formed part way through the substrate 14PGA using a scribing, etching or lasering process, followed by filling with a polymer substantially as previously described for polymer filled trenches 28AP in Figure 8C. In addition, a circuit side polymer layer 36PGA can be formed on the circuit side 20PGA and on the contact bumps 24PGA. The circuit side polymer layer 36PGA can be formed substantially as previously described for circuit side polymer layer 36AP in Figure 9F.